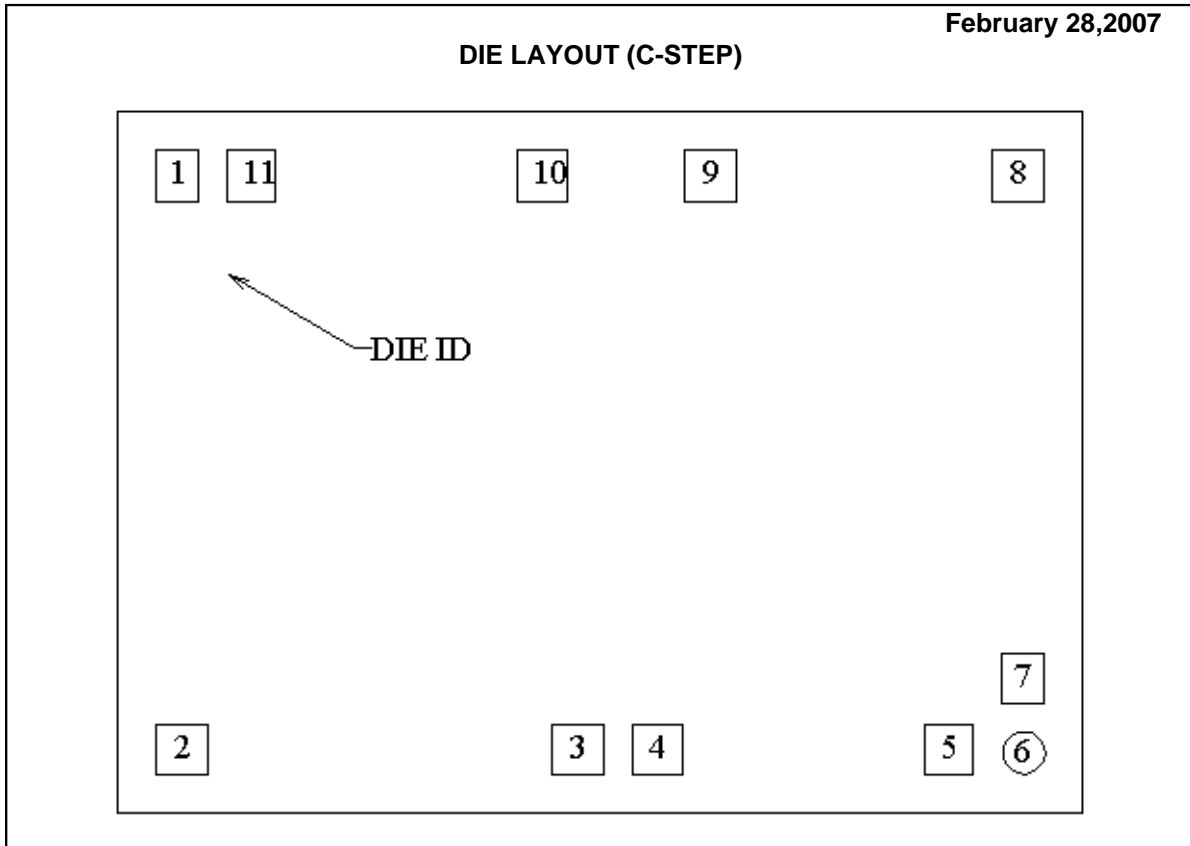


**LM119 MD8 MCD2490A
HIGH SPEED DUAL COMPARATOR**



DIE/WAFER CHARACTERISTICS

| Fabrication Attributes | | General Die Information | |
|-----------------------------|--|-----------------------------|--------------------------|
| Physical Die Identification | 119C | Bond Pad Opening Size (min) | 91 μ m x 109 μ m |
| Die Step | C | Bond Pad Metalization | ALUMINUM |
| Physical Attributes | | Passivation | VOM NITRIDE |
| Wafer Diameter | 100mm | Back Side Metal | Bare Back |
| Die Size (Drawn) | 2057 μ m x 1499 μ m 81.0mils x 59.0mils | Back Side Connection | V- |
| Thickness | 330 μ m Nominal | | |
| Min Pitch | 157 μ m Nominal | | |

Special Assembly Requirements:

Note: Actual die size is rounded to the nearest micron. V- connected to die backside.

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| Die Bond Pad Coordinate Locations (C -Step) | | | | | | |
|---|--------|-----------------|------|----------|---|-----|
| (Referenced to die center, coordinates in μm) NC = No Connection, N.U. = Not Used | | | | | | |
| SIGNAL | PAD# | X/Y COORDINATES | | PAD SIZE | | |
| NAME | NUMBER | X | Y | X | Y | |
| Output 1 | 1 | -902 | 613 | 91 | x | 109 |
| GND 1 | 2 | -893 | -613 | 109 | x | 109 |
| +Input 1 | 3 | -47 | -613 | 109 | x | 109 |
| -Input 1 | 4 | 123 | -613 | 109 | x | 109 |
| V- | 5 | 744 | -613 | 102 | x | 109 |
| NC | 6 | 902 | -622 | 91 | x | 91 |
| Output 2 | 7 | 902 | -461 | 91 | x | 109 |
| Gnd 2 | 8 | 893 | 613 | 109 | x | 109 |
| +Input 2 | 9 | 237 | 613 | 109 | x | 109 |
| -Input 2 | 10 | -123 | 613 | 109 | x | 109 |
| V+ | 11 | -744 | 613 | 102 | x | 109 |

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